

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously Presented) An organic light emitting device comprising:  
a substrate with a device region defined thereon;  
an active component on a surface of the substrate in the device region, wherein the active component includes an organic light emitting diode;  
a cap mounted on the substrate to form a package, the cap creating a cavity over the device region to seal the active component; and  
spacer particles fixed to the active component, the spacer particles preventing the cap from contacting the active component.
2. (Previously Presented) The device of claim 1 wherein the device region comprises one or more cells.
3. (Original) The device of claim 2 wherein the spacer particles comprise a non-conductive material.
4. (Previously Presented) The device of claim 3 wherein the spacer particles are coated with an adhesive layer.
5. (Original) The device of claim 4 wherein the adhesive layer comprises thermal curable material.

6. (Original) The device of claim 4 wherein the adhesive layer comprises ultraviolet curable material.

7. (Original) The device of claim 4 wherein the adhesive layer comprises hot melt material.

8. (Previously Presented) A device comprising:  
a substrate with a device region defined thereon;  
an active component on a surface of the substrate in the device region;  
a cap mounted on the substrate to form a package, the cap creating a cavity over the device region to seal the active component; and  
spacer particles fixed to the active component, the spacer particles preventing the cap from contacting the active component, wherein the spacer particles are coated with an adhesive layer.

9. (Original) The device of claim 8 wherein the adhesive layer comprises thermal curable material.

10. (Original) The device of claim 8 wherein the adhesive layer comprises ultraviolet curable material.

11. (Original) The device of claim 8 wherein the adhesive layer comprises hot melt material.

12. (Original) The device of claims 1, 2, 3, 4, 5, 6, 7, 8, 9, 10 or 11 wherein the spacer particles are randomly distributed in the device region, occupying both active and non-active regions.

13. (Original) The device of claims 1, 2, 3, 4, 5, 6, 7, 8, 9, 10 or 11 wherein the spacer particles are randomly distributed in the device region, selectively occupying non-active regions.

14. (Previously Presented) The device of claim 12 wherein the spacer particles comprise a spherical or non-spherical shape or a combination thereof.

15. (Currently Amended) The device of claim 14 wherein the spacer particles comprise[[s]] a mean diameter to maintain a height of the cavity between the cap and substrate.

16. (Original) The device of claim 15 wherein the spacer particles comprise a density to maintain the cavity.

17-23. (Canceled)

24. (Previously Presented) The device of claim 13 wherein the spacer particles comprise a spherical shape or non-spherical shape or a combination thereof.

25. (Currently Amended) The device of claim 24 wherein the spacer particles comprise[[s]] a mean diameter to maintain a height of the cavity between the cap and substrate.

26. (Original) The device of claim 25 wherein the spacer particles comprise a density to maintain the cavity.

27-55. (Canceled)

56. (Previously Presented) A device comprising:  
a substrate with a device region;  
a sealing dam surrounding the device region;  
a cap supported by the sealing dam;  
spacer particles fixed to a surface of the device region to support the cap;  
a sealing region abutting an outer surface of the sealing dam;  
an adhesive located in the sealing region, the adhesive hermetically sealing the device region.

57. (Previously Presented) The device of claim 56 wherein the device region comprises one or more OLED cells.

58. (Previously Presented) The device of claim 57 wherein the spacer particles comprise a non-conductive material.

59. (Previously Presented) The device of claim 58 wherein the spacer particles are coated with a layer of adhesive.

60. (Previously Presented) The device of claim 56 wherein the spacer particles are coated with a layer of adhesive.

61. (Previously Presented) The device of claims 56, 57, 58, 59 or 60 wherein the spacer particles are randomly distributed in the device region, occupying both active and non-active regions.

62. (Previously Presented) The device of claims 56, 57, 58, 59, or 60 wherein the spacer particles are randomly distributed in the device region, selectively occupying non-active regions.

63. (Previously Presented) The device of claim 61 wherein the spacer particles comprise a spherical or non-spherical shape or a combination thereof.

64. (Previously Presented) The device of claim 63 wherein the spacer particles comprise a mean diameter to maintain a height of the cavity between the cap and substrate.

65. (Previously Presented) The device of claim 64 wherein the spacer particles comprise a density to maintain the cavity.

66. (Previously Presented) The device of claim 62 wherein the spacer particles comprise a spherical or non-spherical shape or a combination thereof.

67. (Previously Presented) The device of claim 66 wherein the spacer particles comprise a mean diameter to maintain a height of the cavity between the cap and substrate.

68. (Previously Presented) The device of claim 67 wherein the spacer particles comprise a density to maintain the cavity.